

Receipt

IR-1881 (2-2532)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Bharat Shivkumar

Date: September 17, 2001

Serial No.: 09/812,027

Group Art Unit: ---

Filed: March 19, 2001

For: SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED
THERMAL PERFORMANCE; REDUCED SIZE AND IMPROVED
MOISTURE RESISTANCE

Asst. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

REQUEST FOR A CORRECTED FILING RECEIPT

Sir:

Please issue a corrected filing receipt for the above application. The original filing receipt includes an error in the inventorship. The address of the second inventor, Chuan Cheah, is El Segundo, CA. A copy of the Declaration and Power of Attorney stating the correct address is attached.

It is requested that the U.S. Patent and Trademark Office issue a corrected filing receipt at the earliest possible date.

In the event payment of any fee is inadvertently not enclosed, or if any additional fee during the prosecution of this case is not paid, the Patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

Respectfully submitted,

Kourosh Salehi

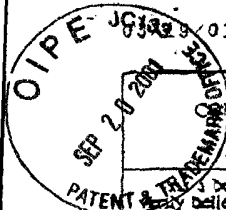
Registration No.: 43,898

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OSTROLENK; FABER

 UNITED STATES OF AMERICA
 COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

 OFGS FILE NO.
 IR-1881
 (2-2532)

I, below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I believe that I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are named) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED THERMAL PERFORMANCE, REDUCED SIZE AND IMPROVED MOISTURE RESISTANCE

the specification of which is attached hereto, unless the following box is checked:

☐ was filed on _____ as United States patent Application Number or PCT International patent application number _____ and was amended on _____ (if any).

I hereby state that I have reviewed and understood the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information known to be material to patentability in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefit under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate or United States provisional application(s) listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign or Provisional Application(s)

COUNTRY	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY CLAIMED UNDER 35 U.S.C. 119
United States	60/190,143	17 March 2000	YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

UNITED STATES APPLICATION NUMBER	DATE OF FILING (day, month, year)	STATUS (pending, pending, abandoned)

I hereby appoint customer no. 2352 OSTROLENK, FABER, GERB & SOFFEN, LLP, and the members of the firm, Samuel H. Weiner - Reg. No. 18,510; Jerome M. Berlinger - Reg. No. 18,653; Robert C. Faber - Reg. No. 24,322; Edward A. Melman - Reg. No. 24,735; Stanley H. Liberman - Reg. No. 22,400; Steven I. Waisbard - Reg. No. 27,409; Max Moskowitz - Reg. No. 30,376; Stephen A. Soffen - Reg. No. 31,063; James A. Pinder - Reg. No. 30,173; William O. Gray, III - Reg. No. 30,944; Louis C. Dymlich - Reg. No. 30,625 and Douglas A. Miro - Reg. No. 31,643, as attorneys with full power of substitution and revocation to prosecute this application, to transact all business in the Patent & Trademark Office connected therewith and to receive all correspondence.

SEND CORRESPONDENCE TO: OSTROLENK, FABER, GERB & SOFFEN, LLP
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that those statements were made with the knowledge that willful false statements and the like as made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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